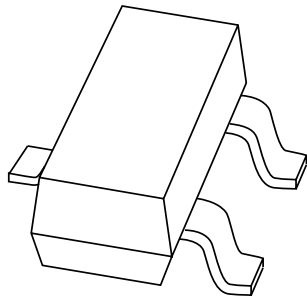


# DATA SHEET



## **BAS17** Low-voltage stabistor

Product data sheet  
Supersedes data of 1999 May 31

2003 Mar 25

# Low-voltage stabistor

# BAS17

## FEATURES

- Low-voltage stabilization
- Forward voltage range: 580 to 960 mV
- Total power dissipation: max. 250 mW.

## APPLICATIONS

- Low-voltage stabilization e.g.
  - Bias stabilizer in class-B output stages
  - Clipping
  - Clamping
  - Meter protection.

## DESCRIPTION

Low-voltage stabilization diode in a small SOT23 plastic package.

## MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BAS17	*A9

## Note

1. \* = p : Made in Hong Kong.  
 \* = t : Made in Malaysia.  
 \* = W : Made in China.

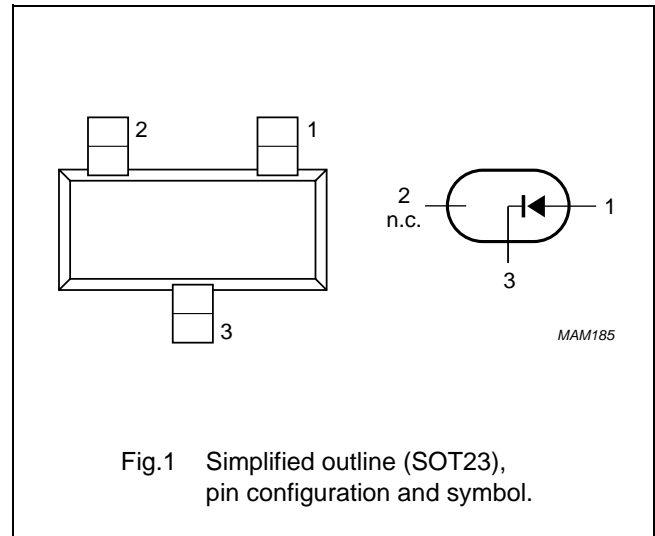
## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		–	5	V
$I_F$	continuous forward current		–	200	mA
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ °C}$	–	250	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C

## PINNING

PIN	DESCRIPTION
1	anode
2	not connected
3	cathode



## Low-voltage stabistor

BAS17

**ELECTRICAL CHARACTERISTICS** $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	forward voltage	see Fig.2				
		$I_F = 0.1\text{ mA}$	580	–	660	mV
		$I_F = 1\text{ mA}$	665	–	745	mV
		$I_F = 5\text{ mA}$	725	–	805	mV
		$I_F = 10\text{ mA}$	750	–	830	mV
		$I_F = 100\text{ mA}$	870	–	960	mV
$I_R$	reverse current	$V_R = 4\text{ V}$	–	–	5	$\mu\text{A}$
$r_{dif}$	differential resistance	$I_F = 0.5\text{ mA}$	–	120	–	$\Omega$
		$I_F = 2\text{ mA}$	–	80	–	$\Omega$
$S_F$	temperature coefficient	$I_F = 1\text{ mA}$	–	–1.8	–	mV/K
$C_d$	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz}$	–	–	140	pF

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-tp}$	thermal resistance from junction to tie-point		330	K/W
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

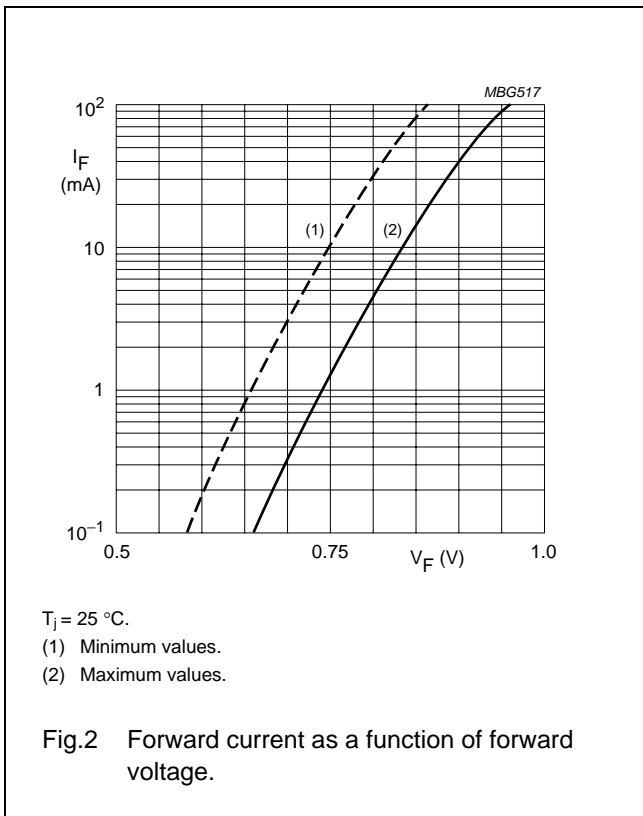
**Note**

1. Device mounted on a FR4 printed-circuit board.

# Low-voltage stabistor

# BAS17

## GRAPHICAL DATA



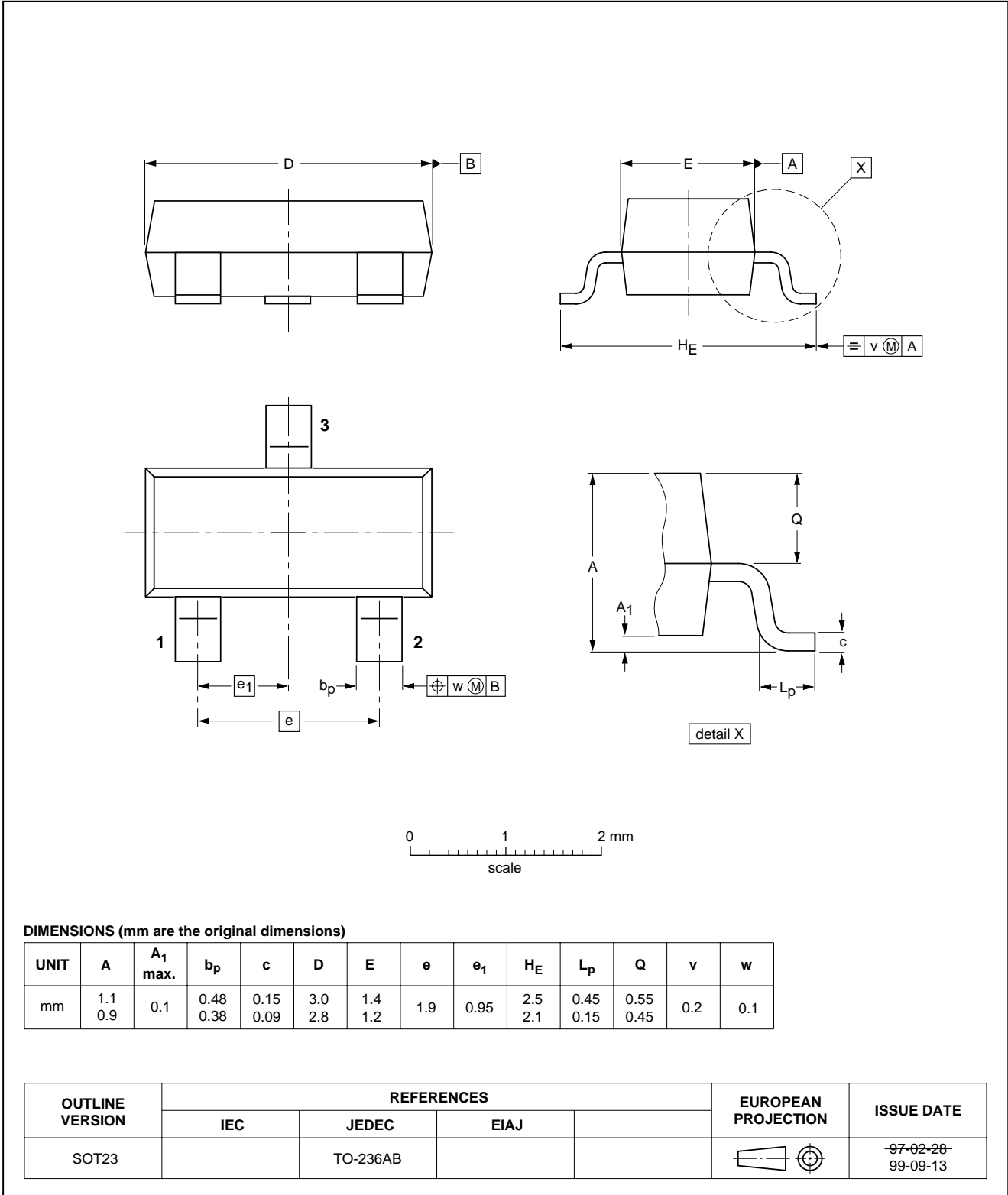
Low-voltage stabistor

BAS17

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



Low-voltage stabistor

BAS17

**DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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## **Contact information**

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Printed in The Netherlands

613514/03/pp7

Date of release: 2003 Mar 25

Document order number: 9397 750 10969

